

General Description

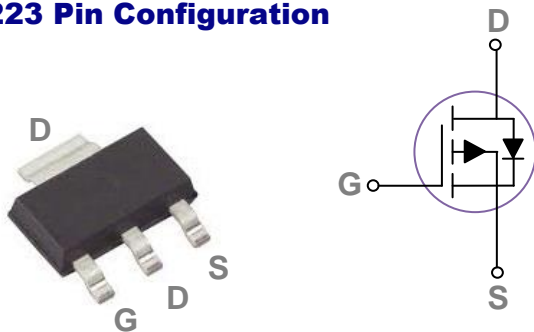
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

| | | |
|-------|---------------------|----------------|
| BVDSS | R _{DS(ON)} | I _D |
| -30V | 55mΩ | -4.5A |

Features

- -30V,-4.5A, R_{DS(ON)} =55mΩ@V_{GS} = -10V
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

SOT223 Pin Configuration



Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

Absolute Maximum Ratings T_c=25°C unless otherwise noted

| Symbol | Parameter | Rating | Units |
|------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | -30 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D | Drain Current – Continuous (T _C =25°C) | -4.5 | A |
| | Drain Current – Continuous (T _C =100°C) | -2.85 | A |
| I _{DM} | Drain Current – Pulsed ¹ | -18 | A |
| P _D | Power Dissipation (T _C =25°C) | 1.78 | W |
| | Power Dissipation – Derate above 25°C | 0.014 | W/°C |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction to ambient | --- | 70 | °C/W |
| R _{θJC} | Thermal Resistance Junction to Case | --- | 45 | °C/W |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|---|---|------|-------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =-250uA | -30 | --- | --- | V |
| ΔBV _{DSS} /ΔT _J | BV _{DSS} Temperature Coefficient | Reference to 25°C, I _D =-1mA | --- | -0.03 | --- | V/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =-30V, V _{GS} =0V, T _J =25°C | --- | --- | -1 | uA |
| | | V _{DS} =-24V, V _{GS} =0V, T _J =125°C | --- | --- | -10 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |

On Characteristics

| | | | | | | |
|----------------------|---|---|------|------|------|-------|
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =-10V, I _D =-4A | --- | 45 | 55 | mΩ |
| | | V _{GS} =-4.5V, I _D =-3A | --- | 65 | 85 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =-250uA | -1.2 | -1.6 | -2.2 | V |
| ΔV _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | 4 | --- | mV/°C |
| gfs | Forward Transconductance | V _{DS} =-10V, I _D =-3A | --- | 3.5 | --- | S |

Dynamic and switching Characteristics

| | | | | | | |
|---------------------|------------------------------------|---|-----|------|-----|----|
| Q _g | Total Gate Charge ^{2,3} | V _{DS} =-15V, V _{GS} =-4.5V, I _D =-3A | --- | 5.1 | 7 | nC |
| Q _{gs} | Gate-Source Charge ^{2,3} | | --- | 2 | 3 | |
| Q _{gd} | Gate-Drain Charge ^{2,3} | | --- | 2.2 | 4 | |
| T _{d(on)} | Turn-On Delay Time ^{2,3} | V _{DD} =-15V, V _{GS} =-10V, R _G =6Ω I _D =-1A | --- | 3.4 | 6 | ns |
| T _r | Rise Time ^{2,3} | | --- | 10.8 | 21 | |
| T _{d(off)} | Turn-Off Delay Time ^{2,3} | | --- | 26.9 | 51 | |
| T _f | Fall Time ^{2,3} | | --- | 6.9 | 13 | |
| C _{iss} | Input Capacitance | V _{DS} =-15V, V _{GS} =0V, F=1MHz | --- | 560 | 810 | pF |
| C _{oss} | Output Capacitance | | --- | 55 | 80 | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 40 | 60 | |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|---------------------------|--|------|------|------|------|
| I _S | Continuous Source Current | V _G =V _D =0V, Force Current | --- | --- | -4.1 | A |
| I _{SM} | Pulsed Source Current | | --- | --- | -8.2 | A |
| V _{SD} | Diode Forward Voltage | V _{GS} =0V, I _S =-1A, T _J =25°C | --- | --- | -1 | V |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

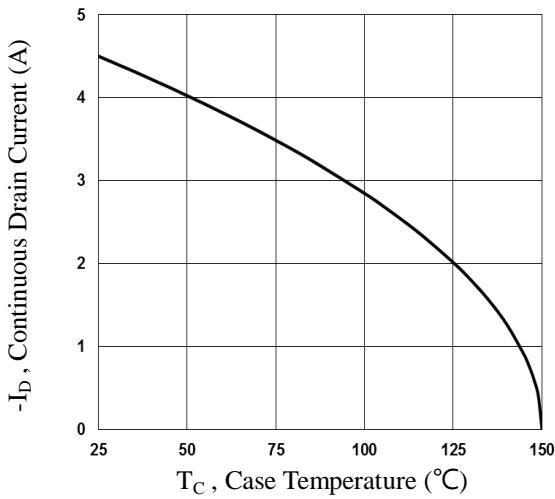


Fig.1 Continuous Drain Current vs. T_c

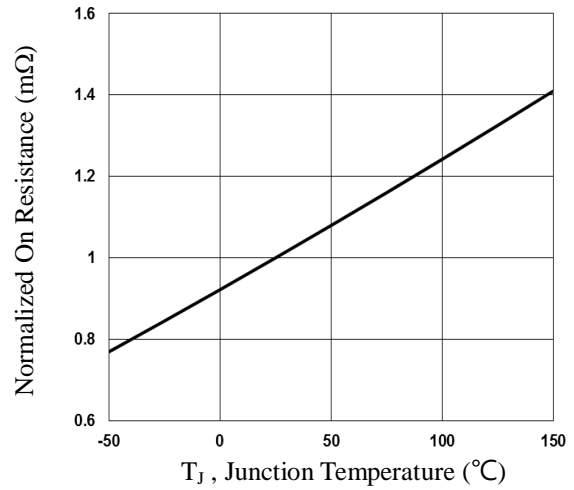


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

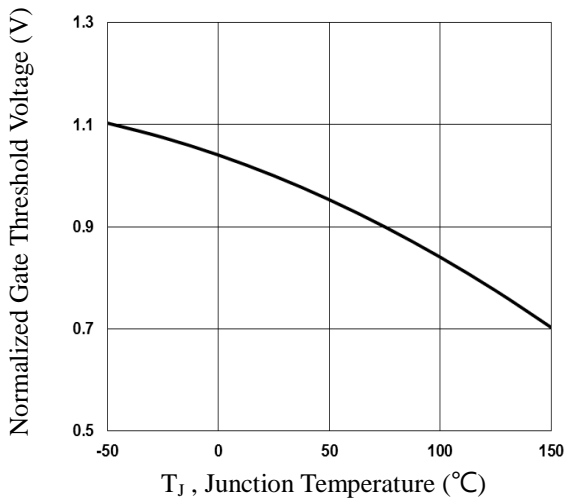


Fig.3 Normalized V_{th} vs. T_j

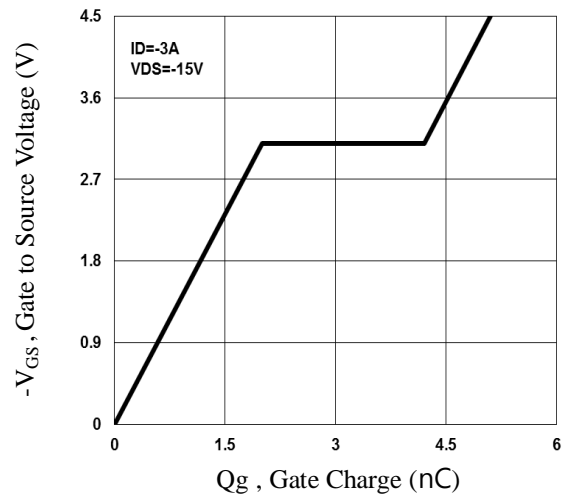


Fig.4 Gate Charge Waveform

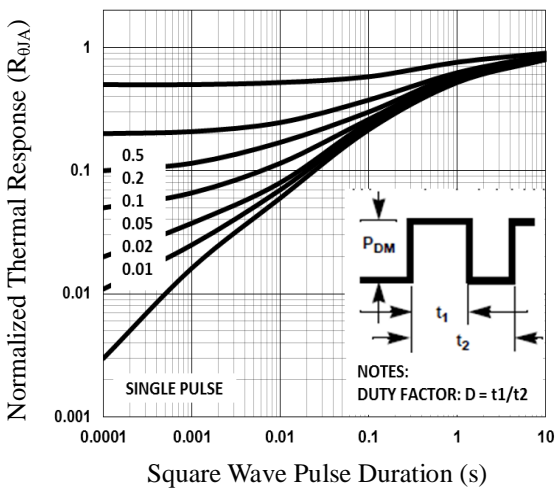


Fig.5 Normalized Transient Impedance

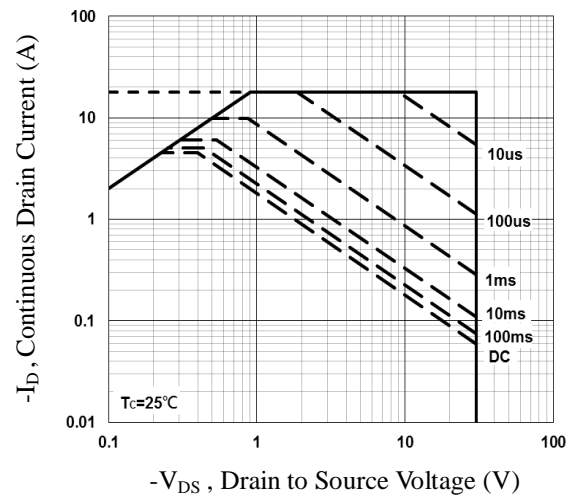


Fig.6 Maximum Safe Operation Area

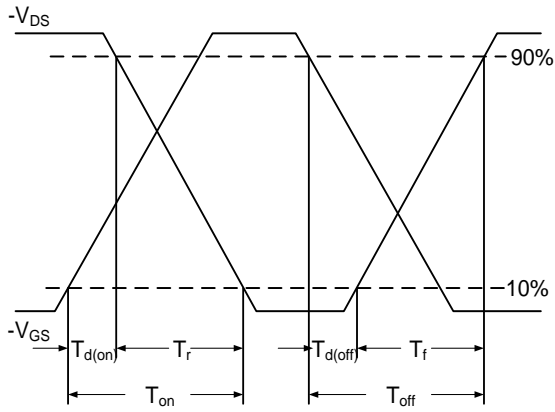


Fig.7 Switching Time Waveform

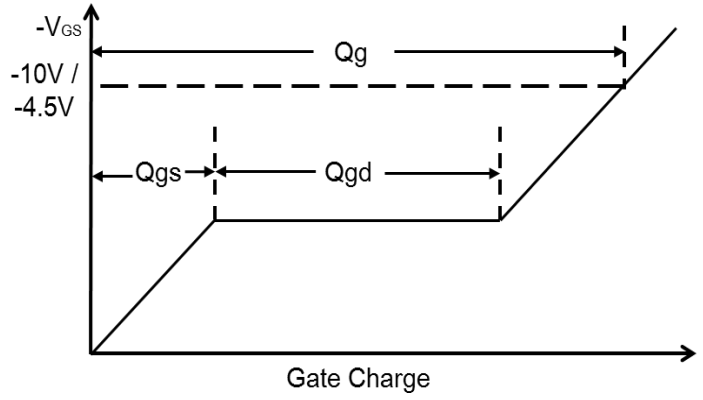
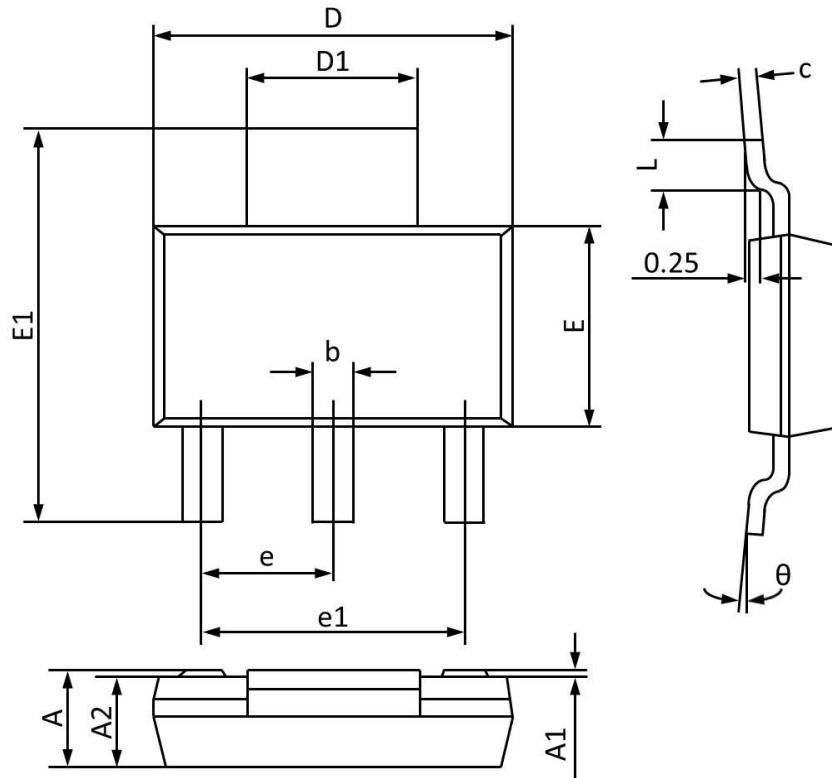


Fig.8 Gate Charge Waveform

SOT223 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | MAX | MIN | MAX | MIN |
| A | 1.800 | 1.520 | 0.071 | 0.060 |
| A1 | 0.100 | 0.000 | 0.004 | 0.000 |
| A2 | 1.700 | 1.500 | 0.067 | 0.059 |
| b | 0.820 | 0.660 | 0.032 | 0.026 |
| c | 0.350 | 0.250 | 0.014 | 0.010 |
| D | 6.400 | 6.200 | 0.252 | 0.244 |
| D1 | 3.100 | 2.900 | 0.122 | 0.114 |
| E | 3.700 | 3.300 | 0.146 | 0.130 |
| E1 | 7.070 | 6.830 | 0.278 | 0.269 |
| e | 2.30(BSC) | | 0.091(BSC) | |
| e1 | 4.700 | 4.500 | 0.185 | 0.177 |
| L | 1.150 | 0.900 | 0.045 | 0.035 |
| θ | 10° | 0° | 10° | 0° |